

WHAT IS CLAIMED IS:

1. A modular array arrangement comprising:  
a carrier; and  
at least one insert for attachment to said carrier, said at least one insert having a first connecting means arranged on or formed in at least one of the external walls of said at least one insert, said carrier having at least one location for receiving one of said at least one insert and comprising a second connecting means, said second connecting means being arranged in, adjacent to, or formed by said at least one location, said first connecting means unambiguously matching with said second connecting means, said unambiguously matching permitting to align said at least one insert in a predetermined orientation in or on said carrier, and said insert having at least one section defined for receiving a sample, said at least one section being provided with or adapted for receiving operational means.
2. The modular array arrangement according to claim 1, wherein said first connecting means is essentially or partially complementary to said second connecting means.
3. The modular array arrangement according to claim 1, wherein said first connecting means or said second connecting means have an asymmetric structure or form.
4. The modular array arrangement according to claim 1, wherein said first connecting means or said second connecting means is adapted to serve as a grip.
5. The modular array arrangement according to claim 1, wherein said insert is releasably or non-releasably connected to said carrier upon attachment to said carrier.
6. The modular array arrangement according to claim 1, wherein an insert is provided with one or more additional first connecting means or an insert receiving location is provided with one or more additional second connecting means.
7. The modular array arrangement according to claim 1, said operational means being selected from the group consisting of compounds attached to the insert surface, media, reagents, solvents, catalysts, coatings, and beads.
8. A modular array arrangement comprising:  
a carrier; and

at least one insert for attachment to said carrier, said at least one insert having a first connecting means arranged on or formed in at least one of the external walls of said at least one insert, said carrier having at least one location for receiving one of said at least one insert and comprising a second connecting means, said second connecting means being arranged in, adjacent to, or formed by to said at least one location, said first connecting means unambiguously matching with said second connecting means, said unambiguously matching permitting to align said at least one insert in a predetermined orientation in or on said carrier, said first connecting means being a projecting element arranged on said insert, said second connecting means being adapted to receive said projecting element, and said insert having at least one section defined for receiving a sample.

9. The modular array arrangement according to claim 8, wherein said first connecting means is essentially or partially complementary to said second connecting means.

10. The modular array arrangement according to claim 8, wherein said first connecting means or said second connecting means have an asymmetric structure or form.

11. The modular array arrangement according to claim 8, wherein said first connecting means or said second connecting means is adapted to serve as a grip.

12. The modular array arrangement according to claim 8, wherein said insert is releasably or non-releasably connected to said carrier upon attachment to said carrier.

13. The modular array arrangement according to claim 8, wherein an insert is provided with one or more additional first connecting means or an insert receiving location is provided with one or more additional second connecting means.

14. An insert for attachment to a carrier, said insert having first connecting means arranged on or formed in at least one of the external walls of said at least one insert, adapted to engage with second connecting means, present in a carrier having at least one location for receiving said insert, said second connecting means being arranged in, adjacent to, or formed by to said at least one location.

15. A method of preparing a modular array arrangement comprising the steps of:  
providing a carrier; and

providing one or more inserts for attachment to said carrier, said at least one insert having a first connecting means arranged on or formed in at least one of the external walls of said at least one insert, said insert having at least one section defined for receiving a sample, said at least one section being provided with or adapted for receiving operational means, and said carrier having at least one location for receiving one of said at least one insert and comprising a second connecting means, said second connecting means being arranged in, adjacent to, or formed by said at least one location, said first connecting means unambiguously matching with said second connecting means.

16. The method of claim 15, said method further comprising the step of contacting said first connecting means with said second connecting means, and thereby aligning said at least one insert in a predetermined orientation in or on said carrier.